

WSK150N10

N-Ch MOSFET

General Description

The WSK150N10 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSK150N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

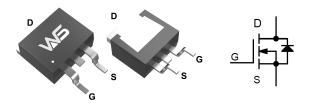
Product Summery

BV _{DSS}	R _{DSON}	I _D
100V	3.7mΩ	150A

Applications

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

TO-263-2L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	100	V	
V _{GS}	Gate-Source Voltage	±25	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	150	А	
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	90	А	
I _{DM}	Pulsed Drain Current ^{2,} T _C =25°C	600	А	
EAS	Avalanche Energy, Single pulse	545	mJ	
I _{AS}	Avalanche Current, Single pulse	60	А	
P _D @T _C =25℃	Total Power Dissipation ⁴	225	W	
T _{STG}	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	150	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
R _{0JA}	Thermal Resistance Junction-Ambient ¹		50	°C/W	
R _{θJC}	Thermal Resistance Junction-Case ¹		0.55	℃/W	



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Electrical Characteristics (TJ=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS} / \triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.096		V/℃
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =80A		3.7	4.2	mΩ
V _{GS(th)}	Gate Threshold Voltage		2.5	3.0	4.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID -2500A		-5.5		mV/℃
la sa	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}80\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			1	uA
I _{DSS}		$V_{\text{DS}}\text{=}80\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}55^\circ\!\mathrm{C}$			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =50A		120		S
R _g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		0.7	1.5	Ω
Qg	Total Gate Charge (10V)			80		
Q _{gs}	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =80A		33		nC
Q _{gd}	Gate-Drain Charge			18		
T _{d(on)}	Turn-On Delay Time			28		
Tr	Rise Time	V_{DD} =50V , V_{GS} =10V ,		55		20
T _{d(off)}	Turn-Off Delay Time	R _G =5Ω, I _D =80A		98		ns
T _f	Fall Time			24		
C _{iss}	Input Capacitance			4120		
Coss	Output Capacitance	V _{DS} =50V , V _{GS} =0V , f=1MHz		1250		pF
C _{rss}	Reverse Transfer Capacitance			65		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	$V_G=V_D=0V$, Force Current			80	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =50A , TJ=25℃		0.8	1.3	V
t _{rr}	Reverse Recovery Time	l ⊧=50A,dl/dt=100A/µs,Tյ=25 ℃		85		nS
Qrr	Reverse Recovery Charge			200		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec. 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2% 3. The EAS data shows Max. rating . The test condition is V_{DS}=80V,V_{GS}=10V,L=0.1mH,

5. The Min. value is 100% EAS tested guarantee.

6.The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

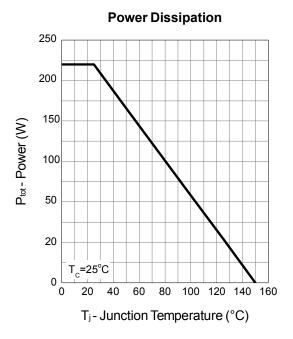
^{4.} The power dissipation is limited by 150 $^\circ\!\mathrm{C}$ junction temperature

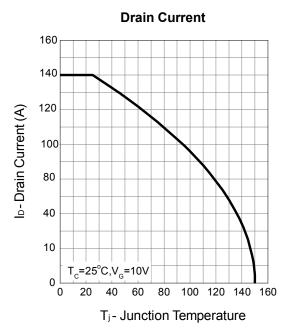


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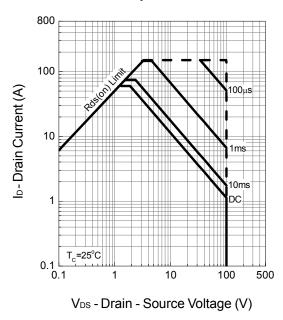
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Typical Operating Characteristics

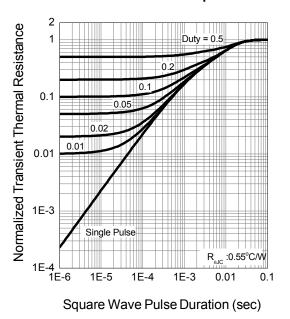




Safe Operation Area



Thermal Transient Impedance

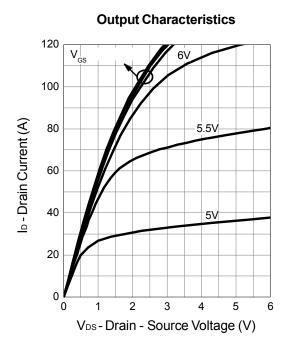




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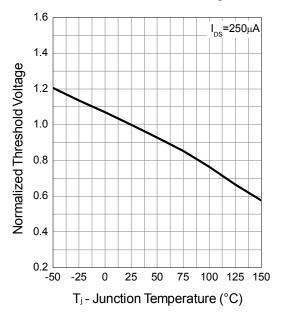
Typical Operating Characteristics



Drain-Source On Resistance

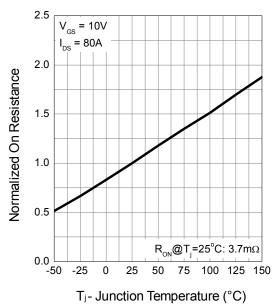
Gate-Source On Resistance 40 I_{DS}=80A 35 $R_{DS(ON)}$ - On - Resistance (m Ω) 30 25 20 15 10 5 6 7 8 9 10 4 VGS - Gate - Source Voltage (V)

Gate Threshold Voltage





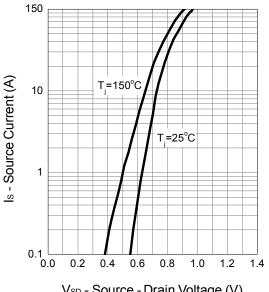
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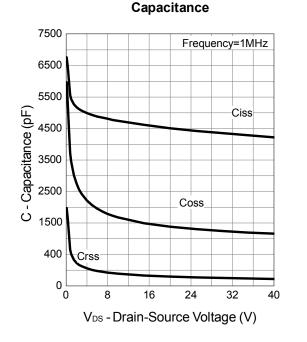
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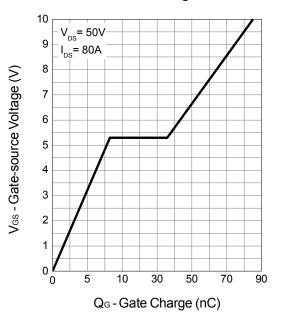


Source-Drain Diode Forward

VsD - Source - Drain Voltage (V)



Gate Charge





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